APPARATUS AND METHOD FOR CONTACT FAILURE INSPECTION IN SEMICONDUCTOR DEVICES

Abstract of the Disclosure

There is provided a contact failure inspection system and method for semiconductor devices and a method of manufacturing semiconductor devices. Using digitized values for electron signals detected using a scanning electron microscope, contacts can be inspected to identify failures such as non-open contact holes. The contact failure inspection is performed by comparing the electron signal value detected from a unit area including at least one contact hole with values representative of the electron signal corresponding to a normal contact.

Figure 1